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JAN 16 2006

**CHIP-PACKAGING WITH BONDING OPTIONS HAVING A PLURALITY OF  
PACKAGE SUBSTRATES**

Appl. No. : 10/709,427 Confirmation No. 3426  
Applicant : Cheng-Yen Huang  
Filed : May 5, 2004  
TC/A.U. : 2822  
Examiner : Prenty, Mark V  
Docket No. : FTCP0036USA0  
Customer No. : 27765

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**AMENDMENT**

5 Sir:

In response to the Office action of November 08, 2005, please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of  
10 this paper.

**Remarks/Arguments** begin on page 5 of this paper.